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### (54) LOW-TEMPERATURE BAKABLE CONDUCTIVE PASTE

(57)Abstract:

PURPOSE: To provide a low-temperature bakable paste which excels in the sintering performance of a copper alloy powder and the strength of adhesion to a substrate by using a glass frit in which a softening point, a crystallizing temperature and a composition are selected.

CONSTITUTION: A conductive paste composed of (A): a copper alloy powder which is expressed by the general formula,  $\text{Ag}_x\text{Cu}_{1-x}$  (wherein  $0.001 \leq x \leq 0.4$ , and (x) is an atomic ratio) and has a region in which the concentration of silver in the surface is higher than the average concentration of the silver and increases towards the surface of a particle, (B): a glass frit having a softening point of 300 to 530°C and a crystallizing temperature of 300 to 600°C and (C): and organic vehicle; is baked at a low temperature. As a result, this paste can be sintered at a low temperature, is high in the strength of adhesion and excellent in the matching performance with a resistive body and the like.